

## General Description

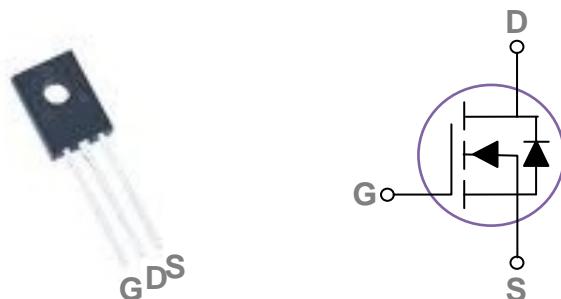
These N-Channel enhancement mode power field effect transistors are planar stripe, DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency switch mode power supply

BVDSS	RDSON	ID
650V	2.6Ω	4A

## Features

- Improved dv/dt capability
- Fast switching
- 100% EAS Guaranteed
- Green Device Available

## TO126 Pin Configuration



## Applications

- High efficient switched mode power supplies
- TV Power
- Adapter/charger
- Server Power
- PV Inverter / UPS

## Absolute Maximum Ratings $T_c=25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	650	V
$V_{GS}$	Gate-Source Voltage	$\pm 30$	V
$I_D$	Drain Current – Continuous ( $T_c=25^\circ\text{C}$ )	4	A
	Drain Current – Continuous ( $T_c=100^\circ\text{C}$ )	2.5	A
$I_{DM}$	Drain Current – Pulsed <sup>1</sup>	16	A
EAS	Single Pulse Avalanche Energy <sup>2</sup>	13	mJ
IAS	Single Pulse Avalanche Current <sup>2</sup>	5	A
$P_D$	Power Dissipation ( $T_c=25^\circ\text{C}$ )	25	W
	Power Dissipation – Derate above $25^\circ\text{C}$	0.2	W/ $^\circ\text{C}$
$T_{STG}$	Storage Temperature Range	-55 to 150	$^\circ\text{C}$
$T_J$	Operating Junction Temperature Range	-55 to 150	$^\circ\text{C}$

## Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction to ambient	---	80	$^\circ\text{C/W}$
$R_{\theta JC}$	Thermal Resistance Junction to Case	---	5	$^\circ\text{C/W}$

**Electrical Characteristics ( $T_J=25^\circ\text{C}$ , unless otherwise noted)**
**Off Characteristics**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$\text{BV}_{\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}$ , $I_D=250\mu\text{A}$	650	---	---	V
$\Delta \text{BV}_{\text{DSS}}/\Delta T_J$	$\text{BV}_{\text{DSS}}$ Temperature Coefficient	Reference to $25^\circ\text{C}$ , $I_D=1\text{mA}$	---	0.5	---	$\text{V}/^\circ\text{C}$
$I_{\text{DSS}}$	Drain-Source Leakage Current	$V_{\text{DS}}=650\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $T_J=25^\circ\text{C}$	---	---	1	$\mu\text{A}$
		$V_{\text{DS}}=520\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $T_J=125^\circ\text{C}$	---	---	10	$\mu\text{A}$
$I_{\text{GSS}}$	Gate-Source Leakage Current	$V_{\text{GS}}=\pm 30\text{V}$ , $V_{\text{DS}}=0\text{V}$	---	---	$\pm 100$	nA

**On Characteristics**

$R_{\text{DS(ON)}}$	Static Drain-Source On-Resistance	$V_{\text{GS}}=10\text{V}$ , $I_D=2\text{A}$	---	2.2	2.6	$\Omega$
$V_{\text{GS(th)}}$	Gate Threshold Voltage	$V_{\text{GS}}=V_{\text{DS}}$ , $I_D=250\mu\text{A}$	3	4	5	V
$\Delta V_{\text{GS(th)}}$	$V_{\text{GS(th)}}$ Temperature Coefficient		---	-8	---	$\text{mV}/^\circ\text{C}$
$g_{\text{fs}}$	Forward Transconductance	$V_{\text{DS}}=10\text{V}$ , $I_D=1\text{A}$	---	4	---	S

**Dynamic and switching Characteristics**

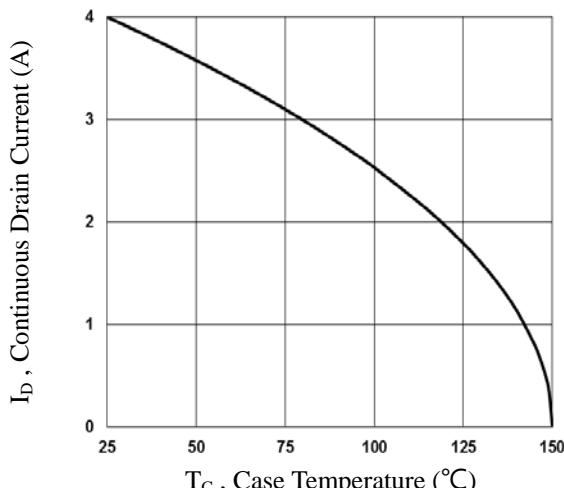
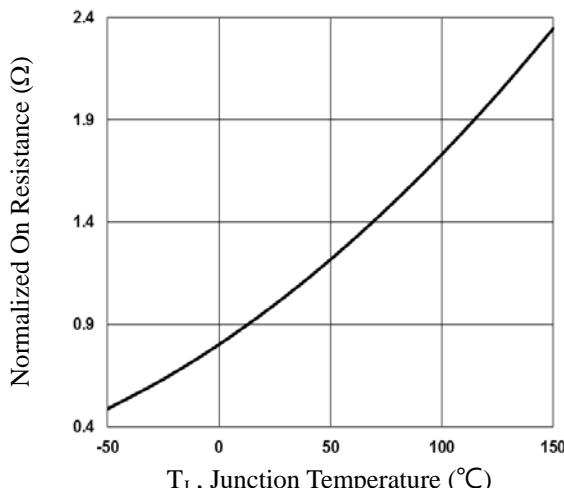
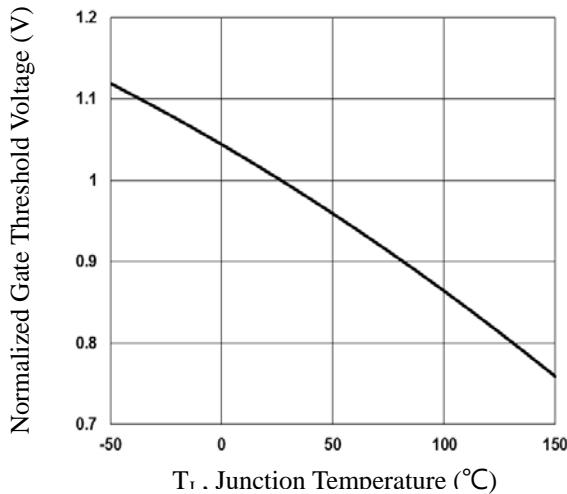
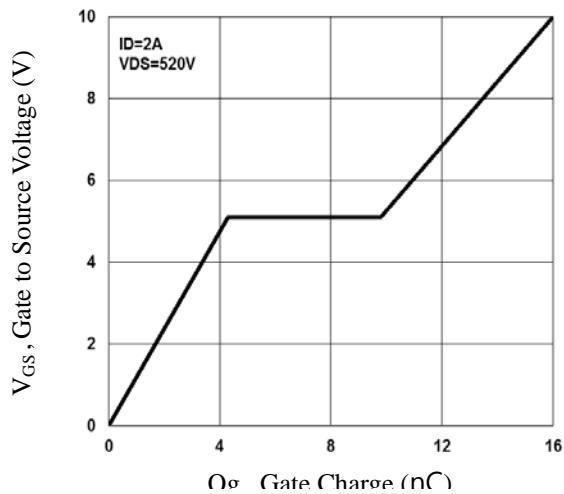
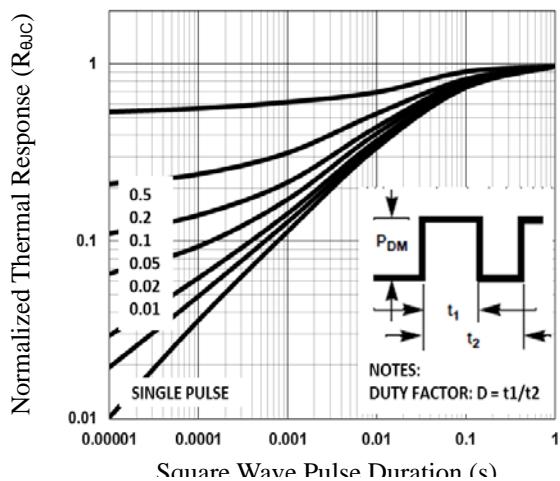
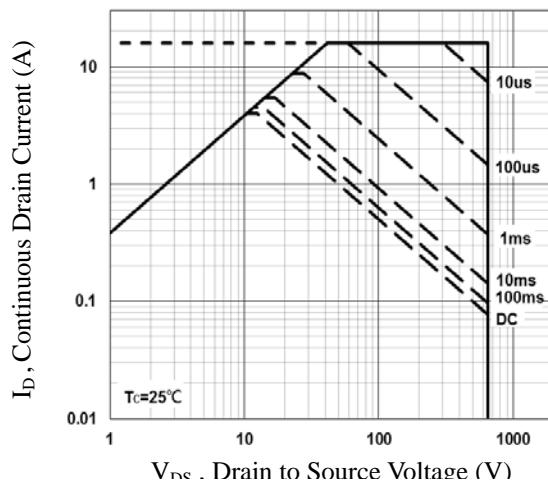
$Q_g$	Total Gate Charge <sup>3,4</sup>	$V_{\text{DS}}=520\text{V}$ , $V_{\text{GS}}=10\text{V}$ , $I_D=2\text{A}$	---	16	24	nC
$Q_{\text{gs}}$	Gate-Source Charge <sup>3,4</sup>		---	4.3	7	
$Q_{\text{gd}}$	Gate-Drain Charge <sup>3,4</sup>		---	5.5	9	
$T_{\text{d(on)}}$	Turn-On Delay Time <sup>3,4</sup>	$V_{\text{DD}}=300\text{V}$ , $V_{\text{GS}}=10\text{V}$ , $R_G=2.2\Omega$ $I_D=1\text{A}$	---	17.8	36	ns
$T_r$	Rise Time <sup>3,4</sup>		---	10.6	20	
$T_{\text{d(off)}}$	Turn-Off Delay Time <sup>3,4</sup>		---	26.5	53	
$T_f$	Fall Time <sup>3,4</sup>		---	26.2	52	
$C_{\text{iss}}$	Input Capacitance	$V_{\text{DS}}=25\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $f=1\text{MHz}$	---	750	1100	pF
$C_{\text{oss}}$	Output Capacitance		---	55	90	
$C_{\text{rss}}$	Reverse Transfer Capacitance		---	4	8	
$R_g$	Gate resistance	$V_{\text{GS}}=0\text{V}$ , $V_{\text{DS}}=0\text{V}$ , $f=1\text{MHz}$	---	2.2	4.4	$\Omega$

**Drain-Source Diode Characteristics and Maximum Ratings**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$I_s$	Continuous Source Current	$V_G=V_D=0\text{V}$ , Force Current	---	---	4	A
$I_{\text{SM}}$	Pulsed Source Current		---	---	16	A
$V_{\text{SD}}$	Diode Forward Voltage	$V_{\text{GS}}=0\text{V}$ , $I_s=1\text{A}$ , $T_J=25^\circ\text{C}$	---	---	1	V
$t_{\text{rr}}$	Reverse Recovery Time <sup>3</sup>	$V_{\text{GS}}=0\text{V}$ , $I_s=1\text{A}$ , $di/dt=100\text{A}/\mu\text{s}$ $T_J=25^\circ\text{C}$	---	---	---	ns
$Q_{\text{rr}}$	Reverse Recovery Charge <sup>3</sup>		---	---	---	$\mu\text{C}$

Note :

1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2.  $V_{\text{DD}}=50\text{V}$ ,  $V_{\text{GS}}=10\text{V}$ ,  $L=1\text{mH}$ ,  $I_{\text{AS}}=5\text{A}$ ,  $R_G=25\Omega$ , Starting  $T_J=25^\circ\text{C}$ .
3. The data tested by pulsed, pulse width  $\leq 300\text{us}$ , duty cycle  $\leq 2\%$ .
4. Essentially independent of operating temperature.


**Fig.1** Continuous Drain Current vs. T<sub>c</sub>

**Fig.2** Normalized RDS(on) vs. T<sub>j</sub>

**Fig.3** Normalized V<sub>th</sub> vs. T<sub>j</sub>

**Fig.4** Gate Charge Waveform

**Fig.5** Normalized Transient Impedance

**Fig.6** Maximum Safe Operation Area

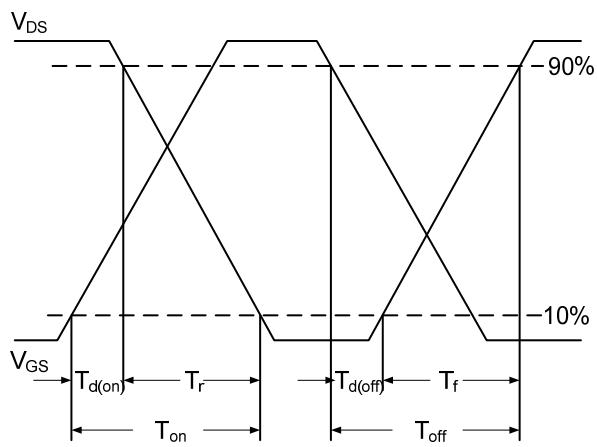


Fig. 7 Switching Time Waveform

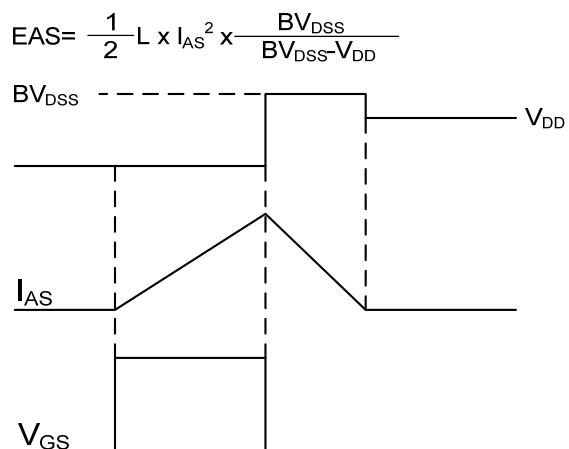
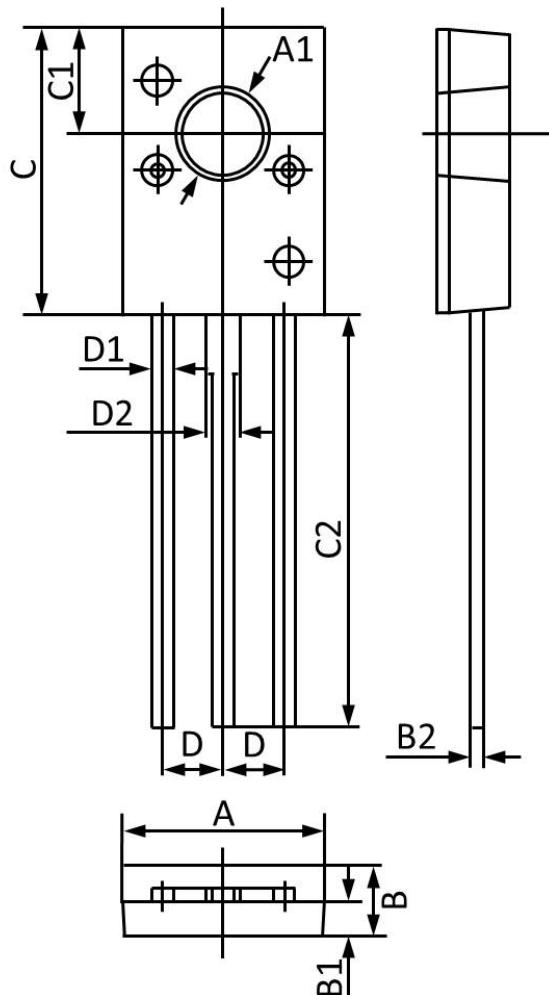


Fig. 8 EAS Waveform

## TO126 PACKAGE INFORMATION



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	7.400	7.800	0.291	0.307
A1	2.950	3.350	0.116	0.132
B	2.900	3.300	0.114	0.130
B1	1.620	1.920	0.064	0.076
B2	0.400	0.600	0.016	0.024
C	10.400	10.800	0.409	0.425
C1	3.060	3.460	0.120	0.136
C2	15.600	16.400	0.614	0.646
D	2.280	2.290	0.089	0.091
D1	0.600	0.800	0.024	0.031
D2	1.150	1.450	0.045	0.057